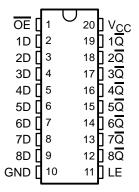
SCLS145C - DECEMBER 1982 - REVISED MARCH 2003

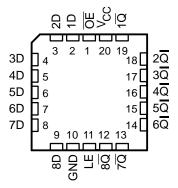
- Wide Operating Voltage Range of 2 V to 6 V
- High-Current 3-State Outputs Drive Bus Lines Directly or Up To 15 LSTTL Loads
- Low Power Consumption, 80-μA Max I_{CC}

SN54HC563...J OR W PACKAGE SN74HC563...DW OR N PACKAGE (TOP VIEW)



- Typical t_{pd} = 21 ns
- ±6-mA Output Drive at 5 V
- Low Input Current of 1 μA Max
- Bus-Structured Pinout

SN54HC563 . . . FK PACKAGE (TOP VIEW)



description/ordering information

These 8-bit transparent D-type latches feature 3-state outputs designed specifically for driving highly capacitive or relatively low-impedance loads. They are particularly suitable for implementing buffer registers, I/O ports, bidirectional bus drivers, and working registers.

While the latch-enable (LE) input is high, the \overline{Q} outputs follow the complements of the data (D) inputs. When LE is taken low, the outputs are latched at the inverses of the levels set up at the D inputs.

A buffered output-enable (\overline{OE}) input places the eight outputs in either a normal logic state (high or low logic levels) or the high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and increased high logic level provide the capability to drive bus lines without interface or pullup components.

To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

OE does not affect internal operations of the latches. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

ORDERING INFORMATION

TA	PACKAC	SE†	ORDERABLE PART NUMBER	TOP-SIDE MARKING
	PDIP – N	Tube	SN74HC563N	SN74HC563N
–40°C to 85°C	SOIC - DW	Tube	SN74HC563DW	HC563
	SOIC - DW	Tape and reel	SN74HC563DWR	псэвэ
	CDIP – J	Tube	SNJ54HC563J	SNJ54HC563J
–55°C to 125°C	CFP – W	Tube	SNJ54HC563W	SNJ54HC563W
	LCCC – FK	Tube	SNJ54HC563FK	SNJ54HC563FK

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

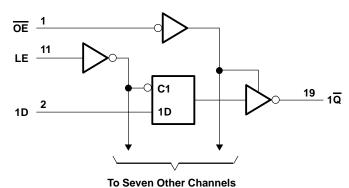


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FUNCTION TABLE (each latch)

	INPUTS		OUTPUT
OE	LE	D	Q
L	Н	Н	L
L	Н	L	Н
L	L	Χ	\overline{Q}_0
Н	X	Χ	Z

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}	–0.5 V to 7 V
Input clamp current, I _{IK} (V _I < 0 or V _I > V _{CC}) (see Note 1)	±20 mA
Output clamp current, I _{OK} (V _O < 0 or V _O > V _{CC}) (see Note 1)	±20 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC})	±35 mA
Continuous current through V _{CC} or GND	±70 mA
Package thermal impedance, θ_{JA} (see Note 2): DW package	58°C/W
N package	69°C/W
Storage temperature range, T _{sto}	–65°C to 150°C

[‡] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

2. The package thermal impedance is calculated in accordance with JESD 51-7.



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recommended operating conditions (see Note 3)

			SN	154HC56	3	SN	174HC56	3	UNIT
			MIN	NOM	MAX	MIN	NOM	MAX	UNIT
Vcc	Supply voltage		2	5	6	2	5	6	V
		V _{CC} = 2 V	1.5			1.5			
ViH	High-level input voltage	V _{CC} = 4.5 V	3.15		ςh	3.15			V
		V _{CC} = 6 V	4.2	17		4.2			
		V _{CC} = 2 V		2	0.5			0.5	
VIL	Low-level input voltage	V _{CC} = 4.5 V) ()	1.35			1.35	V
		VCC = 6 V	2	2	1.8			1.8	
٧ı	Input voltage		0		VCC	0		VCC	V
٧o	Output voltage		0		VCC	0		VCC	V
		V _{CC} = 2 V			1000			1000	
t _t	Input transition (rise and fall) time	V _{CC} = 4.5 V			500			500	ns
		V _{CC} = 6 V			400			400	
TA	Operating free-air temperature		-55		125	-40	_	85	°C

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DADAMETED	TEST CO	NDITIONS	Vaa	Т	A = 25°C	;	SN54H	IC563	SN74H	C563	LINIT
PARAMETER	1251 66	ONDITIONS	VCC	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
			2 V	1.9	1.998		1.9		1.9		
		$I_{OH} = -20 \mu A$	4.5 V	4.4	4.499		4.4	1	4.4		
Voн	$V_I = V_{IH}$ or V_{IL}		6 V	5.9	5.999		5.9	Vie	5.9		V
		$I_{OH} = -6 \text{ mA}$	4.5 V	3.98	4.3		3.7	PR	3.84		
		$I_{OH} = -7.8 \text{ mA}$	6 V	5.48	5.8		5.2		5.34		
			2 V		0.002	0.1	22	0.1		0.1	
		$I_{OL} = 20 \mu A$	4.5 V		0.001	0.1	70	0.1		0.1	
V _{OL}	$V_I = V_{IH}$ or V_{IL}		6 V		0.001	0.1	Q	0.1		0.1	V
		$I_{OL} = 6 \text{ mA}$	4.5 V		0.17	0.26		0.4		0.33	
		$I_{OL} = 7.8 \text{ mA}$	6 V		0.15	0.26		0.4		0.33	
lį	$V_I = V_{CC}$ or 0		6 V		±0.1	±100		±1000		±1000	nA
loz	$V_O = V_{CC}$ or 0		6 V		±0.01	±0.5		±10		±5	μΑ
Icc	$V_I = V_{CC}$ or 0,	IO = 0	6 V			8		160		80	μΑ
Ci			2 V to 6 V		3	10		10		10	pF

SN54HC563, SN74HC563 OCTAL TRANSPARENT D-TYPE LATCHES WITH 3-STATE OUTPUTS

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timing requirements over recommended operating free-air temperature range (unless otherwise noted)

		Vaa	T _A = 2	25°C	SN54F	IC563	SN74H	IC563	UNIT
		VCC	MIN	MAX	MIN	MAX	MIN	MAX	UNIT
		2 V	80		120		100		
t _W	Pulse duration, LE high	4.5 V	16		24	EW	20		ns
		6 V	14		20	FU	17		
		2 V	50		75	Q.	63		
t _{su}	Setup time, data before LE↓	4.5 V	10		15	_/	13		ns
		6 V	9		13		11		
		2 V	5		5		5		
t _h	Hold time, data after LE \downarrow	4.5 V	5		5		5		ns
		6 V	5		5		5		

switching characteristics over recommended operating free-air temperature range, C_L = 50 pF (unless otherwise noted) (see Figure 1)

DADAMETER	FROM	то	V	T,	√ = 25°C	;	SN54H	C563	SN74F	IC563	LINIT														
PARAMETER	(INPUT)	(OUTPUT)	VCC	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT														
			2 V		77	175		265		220															
	D	Q	4.5 V		26	35		53		44															
			6 V		23	30		45		37	20														
^t pd			2 V		90	175		265		220	ns														
	LE	Any Q	4.5 V		27	35	4	53		44															
			6 V		23	30	27/	45																	
			2 V		70	150	70,	225		190															
t _{en}	ŌĒ	Any Q	4.5 V		24	30	d	45		38	ns														
			6 V		21	26		38		32															
			2 V		47	150		225		190															
^t dis	ŌĒ	Any Q	4.5 V		23	30		45		38	ns														
		6 V		21	26		38		32																
				Any Q	Any Q	2 V		28	60		90		75												
t _t	t _t	Any Q	Any Q			Any Q	4.5 V		8	12		18													
			6 V		6	10		15		13															

SN54HC563, SN74HC563 OCTAL TRANSPARENT D-TYPE LATCHES WITH 3-STATE OUTPUTS

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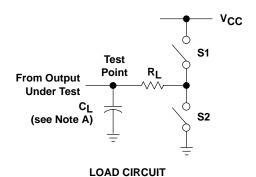
switching characteristics over recommended operating free-air temperature range, C_L = 150 pF (unless otherwise noted) (see Figure 1)

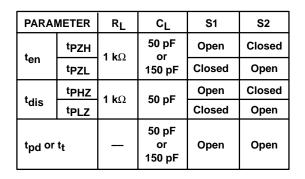
PARAMETER	FROM	то	V	T,	չ = 25°C	;	SN54H	IC563	SN74H	C563	UNIT							
PARAMETER	(INPUT)	(OUTPUT)	VCC	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNII							
			2 V		95	200		300		250								
	D	Q	4.5 V		33	40		60		50								
. .	^t pd LE		6 V		29	34		51		43								
¹ pd				2 V		103	225		335		285	ns						
		Any Q	4.5 V		33	45		67		57								
			6 V		29	38	2	57		48								
		Any $\overline{\overline{Q}}$	2 V		85	200	70	300		250								
t _{en}	ŌĒ		Any Q	4.5 V		29	40	9	60		50	ns						
			6 V		26	34		51		43								
			2 V		60	210		315		265								
t _t				Any Q	Any Q	Any Q	Any Q	Any Q	Any Q	4.5 V		17	42		63		53 ns	ns
			6 V		14	36		53		45								

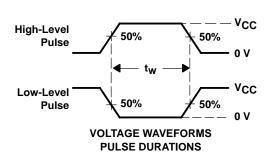
operating characteristics, $T_A = 25^{\circ}C$

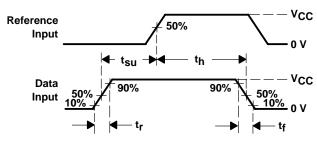
	PARAMETER	TEST CONDITIONS	TYP	UNIT
C _{pd}	Power dissipation capacitance per latch	No load	50	pF

PARAMETER MEASUREMENT INFORMATION

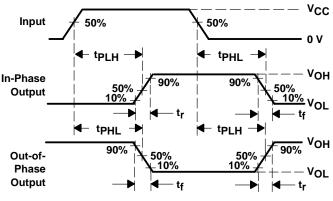


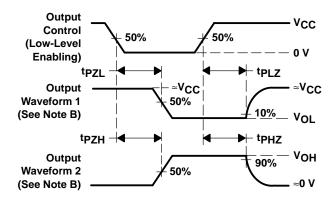






VOLTAGE WAVEFORMS
SETUP AND HOLD AND INPUT RISE AND FALL TIMES





VOLTAGE WAVEFORMS
PROPAGATION DELAY AND OUTPUT TRANSITION TIMES

VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES FOR 3-STATE OUTPUTS

NOTES: A. C_L includes probe and test-fixture capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, Z_O = 50 Ω , t_f = 6 ns, t_f = 6 ns.
- D. The outputs are measured one at a time with one input transition per measurement.
- E. tpLZ and tpHZ are the same as tdis.
- F. tpzL and tpzH are the same as ten.
- G. tpLH and tpHL are the same as tpd.

Figure 1. Load Circuit and Voltage Waveforms







10-Jun-2014

PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package Drawing		Package Qty	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
SN74HC563DW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC563	Samples
SN74HC563DWG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC563	Samples
SN74HC563DWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC563	Samples
SN74HC563DWRG4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC563	Samples
SN74HC563N	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-40 to 85	SN74HC563N	Samples
SN74HC563NE4	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-40 to 85	SN74HC563N	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes. **Pb-Free** (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.



PACKAGE OPTION ADDENDUM

10-Jun-2014

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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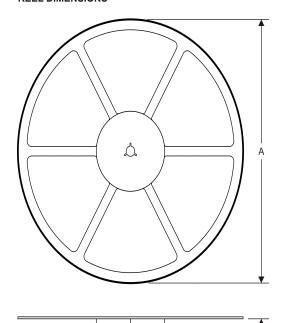
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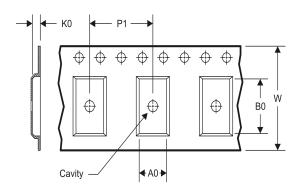
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TAPE AND REEL INFORMATION

REEL DIMENSIONS



TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

TAPE AND REEL INFORMATION

*All dimensions are nominal

Device	Package Type	Package Drawing			Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74HC563DWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.0	2.7	12.0	24.0	Q1

www.ti.com 14-Jul-2012



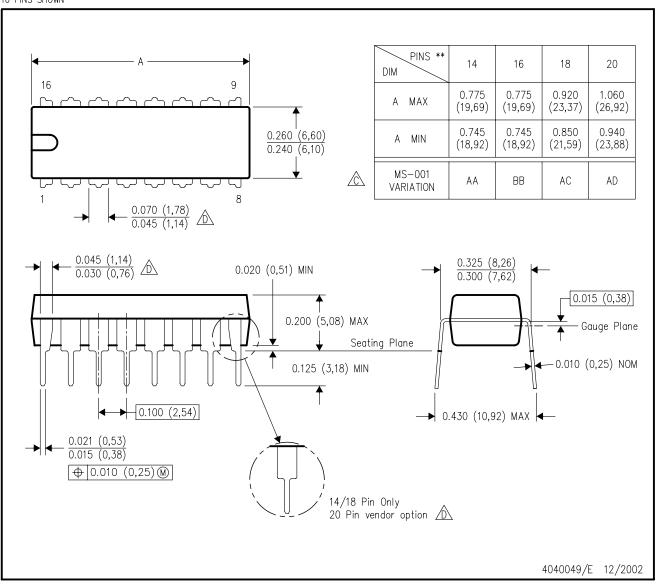
*All dimensions are nominal

ĺ	Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
	SN74HC563DWR	SOIC	DW	20	2000	367.0	367.0	45.0

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



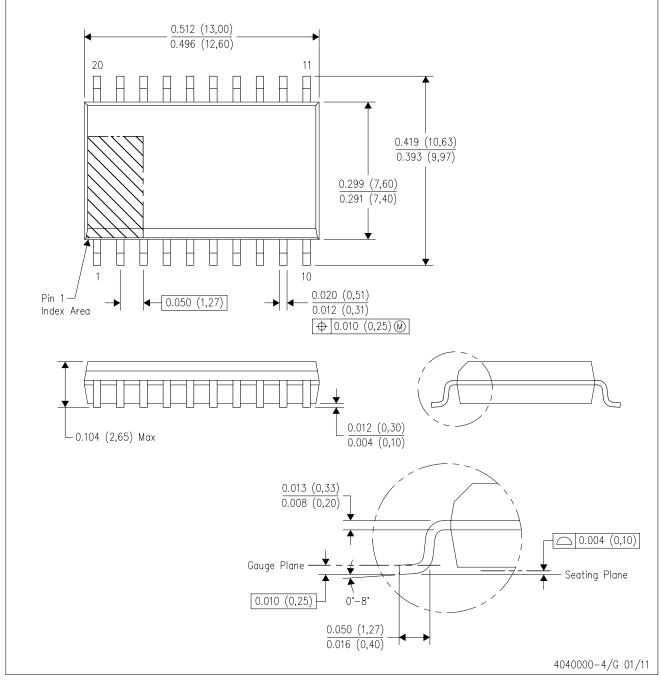
NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



DW (R-PDSO-G20)

PLASTIC SMALL OUTLINE



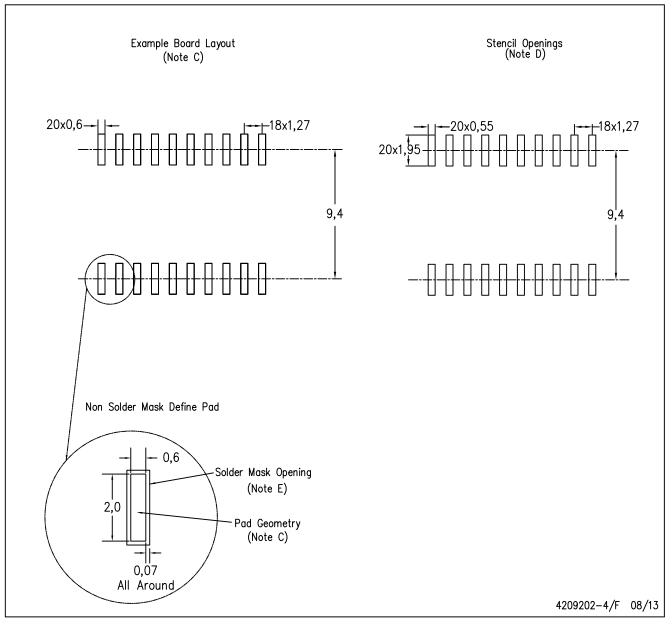
NOTES: A. All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M-1994.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-013 variation AC.



DW (R-PDSO-G20)

PLASTIC SMALL OUTLINE



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Refer to IPC7351 for alternate board design.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



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